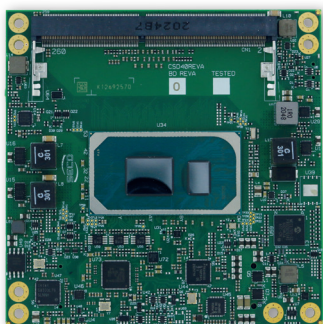




SOM-COMe-CT6-TGL-U

COM Express® Rel. 3.0 Compact Type 6 Module with 11th Gen Intel® Core™ (Codename: Tiger Lake UP3) Processors

High-performance, responsive CPU and GPU compute in COM Express® Compact form factor



HIGHLIGHTS



CPU

Intel® Core™ Series (formerly Tiger Lake UP3) Processors



GRAPHICS

Integrated Intel® Iris® Xe Graphics, up to 96 Execution Units



CONNECTIVITY

1x GbE, 4x SuperSpeed USB 5Gbps; 8x USB 2.0; 8x PCI-e x1 Gen3; PEG x4 Gen4



MEMORY

Two DDR4 SO-DIMM Slots supporting DDR4-3200 IB ECC memory, up to 64GB

Available in Industrial Temperature Range



MAIN FIELDS OF APPLICATION



Medical



Transportation



Industrial
Automation



Digital Signage

FEATURES

Processor	Intel® Core™ i7-1185G7E, Quad Core @2.8GHz (4.4GHz Turbo Boost), 12MB Cache, 28W TDP (12W cTDP), with Hyperthreading	Video Interfaces	Up to 3x Digital Display Interfaces (DDIs), supporting DP 1.2, eDP 1.4, HDMI® 1.4, DVI	
	Intel® Core™ i5-1145G7E, Quad Core @2.6GHz (4.1GHz Turbo Boost), 8MB Cache, 28W TDP (12W cTDP), with Hyperthreading		1 x eDP 1.4 or Single/Dual-Channel 18-/24-bit LVDS interface	
Chipset	Intel® Core™ i3-1115G4E, Dual Core @3.0GHz (3.9GHz Turbo Boost), 6MB Cache, 28W TDP (12W cTDP), with Hyperthreading	Video Resolution	eDP, DP:	up to 5120x3200 @60Hz 24bpp / 7680x4320 @60Hz 30bpp with DSC
	Intel® Core™ i7-1185GRE, Quad Core @2.8GHz (4.4GHz Turbo Boost), 12MB Cache, with IB ECC, 28W TDP (12W cTDP), with Hyperthreading - Industrial		HDMI®:	up to 4096x2160 @24Hz, 24bpp
Memory	Intel® Core™ i5-1145GRE, Quad Core @2.6GHz (4.1GHz Turbo Boost), 8MB Cache, with IB ECC, 28W TDP (12W cTDP), with Hyperthreading - Industrial	Mass Storage	LVDS:	up to 1920x1200 @60Hz
	Intel® Core™ i3-1115GRE, Dual Core @3.0GHz (3.9GHz Turbo Boost), 6MB Cache, with IB ECC, 28W TDP (12W cTDP), with Hyperthreading - Industrial		VGA:	up to 2048 x 1536 @50Hz
Graphics	Intel® Iris® Xe Graphics, up to 96 Execution Units	Networking	2x SATA Gen3 channels	
	Up to 4 independent displays supported		2x PCI-e x4 ports available for M.2 NVMe drives	
	Support DirectX 12, OpenGL 4.6, OpenCL 3.0 and Vulkan 1.2	USB	Gigabit Ethernet interface	
	HW accelerated video decode AVC/H.264, HEVC/H.265, VP8, VP9, AV1		Intel® I225 GbE controller	
	HW accelerated video encode AVC/H.264, HEVC/H.265, VP8, VP9	PCI-e	4x SuperSpeed USB 5Gbps host ports	
			8x USB 2.0 Host ports	
		Audio	8x PCI-e x1 Gen3 lanes	
			PCI-express Graphics (PEG) x4 Gen4	
		Serial Ports	HD audio interface	
			2x UARTs	
		Other Interfaces	SPI, I2C, SM bus, thermal management, FAN management	
			LPC bus	
		Power Supply	Optional TPM 2.0 on-board	
			LID#/SLEEP#/PWRBTN#, Watchdog	
		Operating System	4x GPI, 4x GPO	
			+12V _{DC} ± 10%, +5V _{SB} (optional), +3VRTC (optional)	
			Microsoft® Windows 10	
			Microsoft® Windows 10 IoT Core	
			Linux	

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	Operating Temperature*	0°C ÷ +60°C (Commercial) -40°C ÷ +85°C (Industrial)
	Dimensions	95 x 95 mm (COM Express® Compact Form factor, Type 6 pinout)

*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.

BLOCK DIAGRAM

